P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	- 30
$R_{DS(on)}$ (Ω) at V_{GS} = - 10 V	0.0085
$R_{DS(on)}$ (Ω) at V_{GS} = - 4.5 V	0.0200
I_D (A)	- 22
Configuration	Single

FEATURES

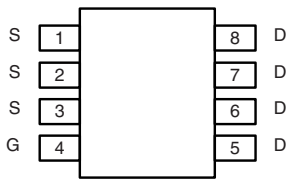
- TrenchFET® Power MOSFET
- ESD Protection: 3000 V
- 100 % R_g and UIS Tested
- AEC-Q101 Qualified[c]

Pb-free

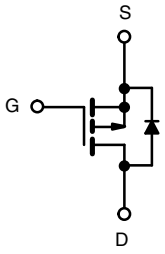
RoHS COMPLIANT

HALOGEN FREE

SO-8



Top View



P-Channel MOSFET

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and Halogen-free	DTM4483

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current	T_C = 25 °C	I_D	- 22	A
	T_C = 125 °C		- 13	
Continuous Source Current (Diode Conduction)		I_S	- 6	
Pulsed Drain Current[a]		I_{DM}	- 84	
Single Pulse Avalanche Current	L = 0.1 mH	I_{AS}	- 50	
Single Pulse Avalanche Energy		E_{AS}	125	mJ
Maximum Power Dissipation[a]	T_C = 25 °C	P_D	7	W
	T_C = 125 °C		2	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS

PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount[b]	R_{thJA}	85	°C/W
Junction-to-Foot (Drain)		R_{thJF}	21	

Notes

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. When mounted on 1" square PCB (FR-4 material).
c. Parametric verification ongoing.

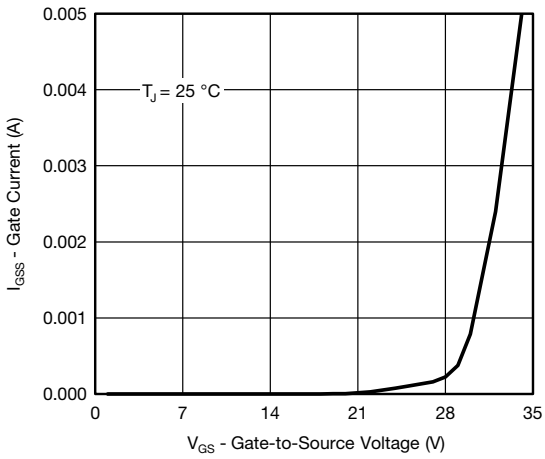
SPECIFICATIONS (T_C = 25 °C, unless otherwise noted)							
PARAMETER	**SYMBOL**	**TEST CONDITIONS**		**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = - 250 µA		- 30	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = - 250 µA		- 1.5	- 2.0	- 2.5	
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V		-	-	± 1	mA
		V_{DS} = 0 V, V_{GS} = ± 12 V		-	-	± 2	µA
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V	V_{DS} = - 30 V	-	-	- 1	
		V_{GS} = 0 V	V_{DS} = - 30 V, T_J = 125 °C	-	-	- 50	
		V_{GS} = 0 V	V_{DS} = - 30 V, T_J = 175 °C	-	-	- 150	
On-State Drain Current[a]	$I_{D(on)}$	V_{GS} = - 10 V	V_{DS} ≤ - 5 V	- 30	-	-	A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = - 10 V	I_D = - 10 A	-	0.0070	0.0085	Ω
		V_{GS} = - 10 V	I_D = - 10 A, T_J = 125 °C	-	-	0.0130	
		V_{GS} = - 10 V	I_D = - 10 A, T_J = 175 °C	-	-	0.0150	
		V_{GS} = - 4.5 V	I_D = - 7 A	-	0.0160	0.0200	
Forward Transconductance[b]	g_{fs}	V_{DS} = - 10 V, I_D = - 10 A		-	32	-	S
Dynamic[b]							
Output Capacitance	C_{oss}	V_{GS} = 0 V	V_{DS} = - 15 V, f = 1 MHz	-	712	890	pF
Total Gate Charge[c]	Q_g	V_{GS} = - 10 V	V_{DS} = - 15 V, I_D = - 10 A	-	75	113	nC
Gate-Source Charge[c]	Q_{gs}			-	9.5	-	
Gate-Drain Charge[c]	Q_{gd}			-	19	-	
Gate Resistance	R_g	f = 1 MHz		6	12.82	20	Ω
Turn-On Delay Time[c]	$t_{d(on)}$	V_{DD} = - 15 V, R_L = 1.5 Ω I_D ≅ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		-	38	57	ns
Rise Time[c]	t_r			-	82	123	
Turn-Off Delay Time[c]	$t_{d(off)}$			-	134	201	
Fall Time[c]	t_f			-	178	214	
Source-Drain Diode Ratings and Characteristics[b]							
Pulsed Current[a]	I_{SM}			-	-	- 84	A
Forward Voltage	V_{SD}	I_F = - 3 A, V_{GS} = 0 V		-	- 0.75	- 1.2	V

Notes

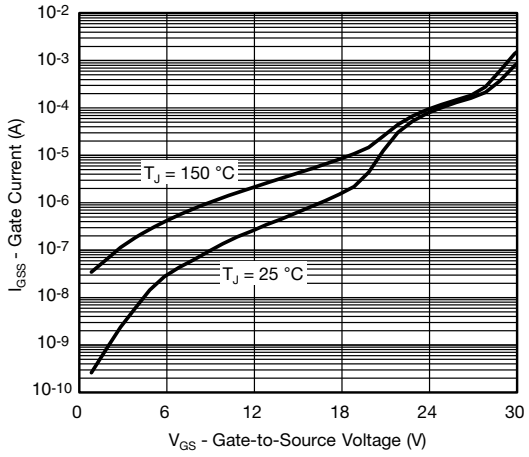
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

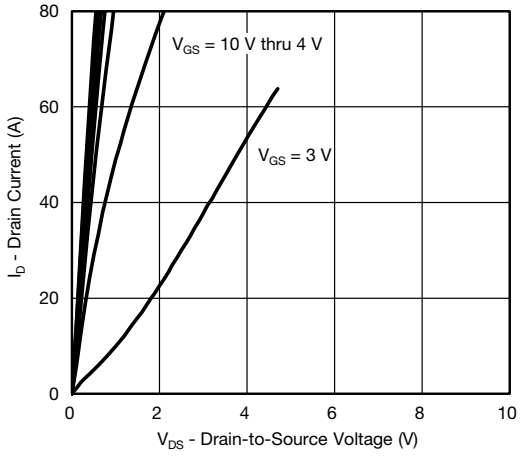
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



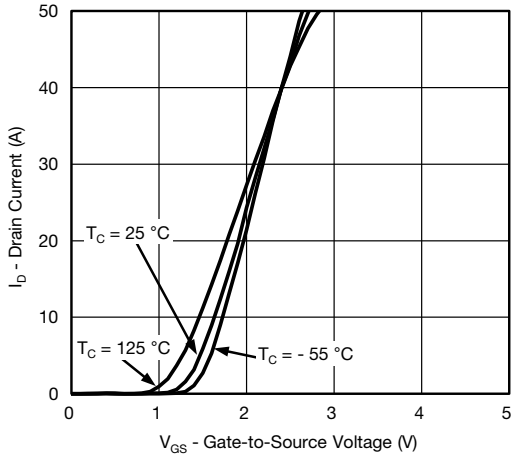
Gate Current vs. Gate-Source Voltage



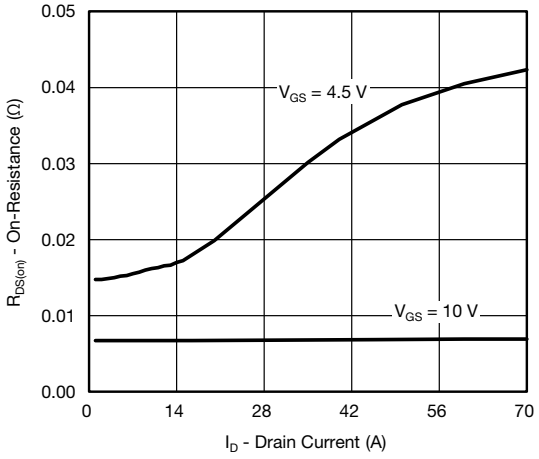
Gate Current vs. Gate-Source Voltage



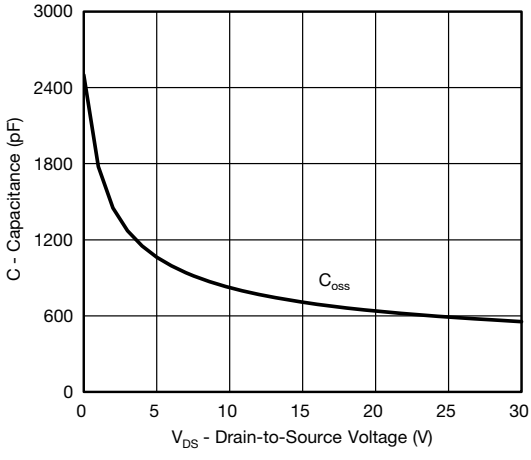
Output Characteristics



Transfer Characteristics

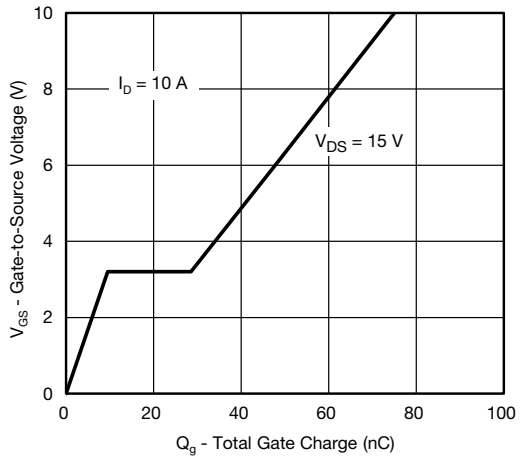


On-Resistance vs. Drain Current

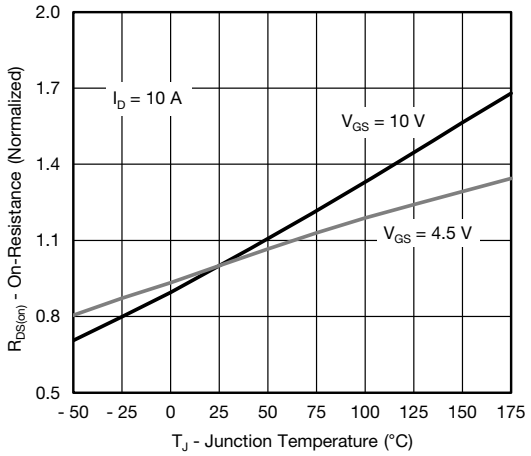


Capacitance

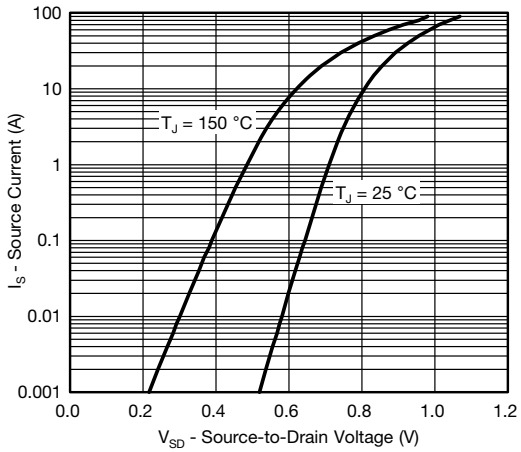
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



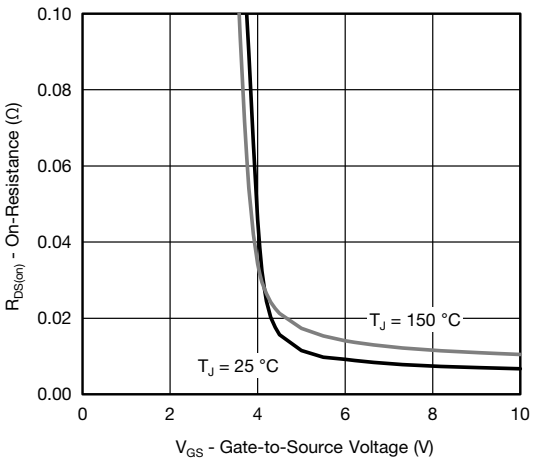
Gate Charge



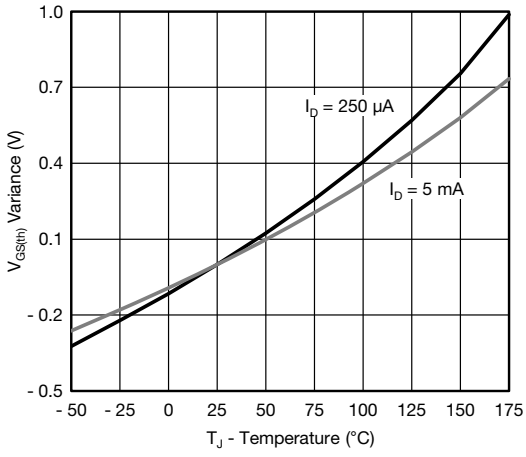
On-Resistance vs. Junction Temperature



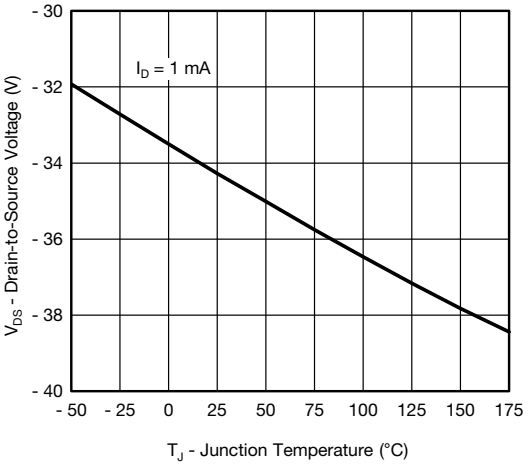
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

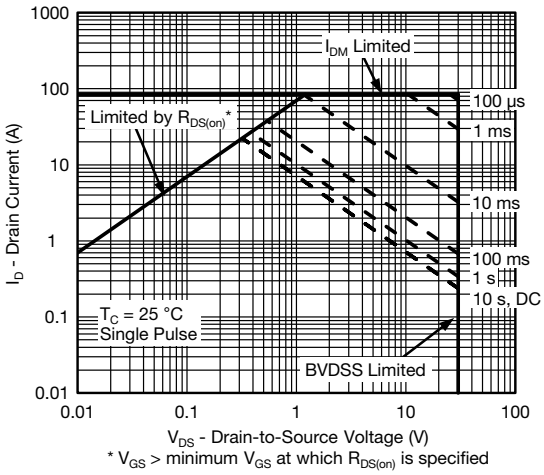


Threshold Voltage

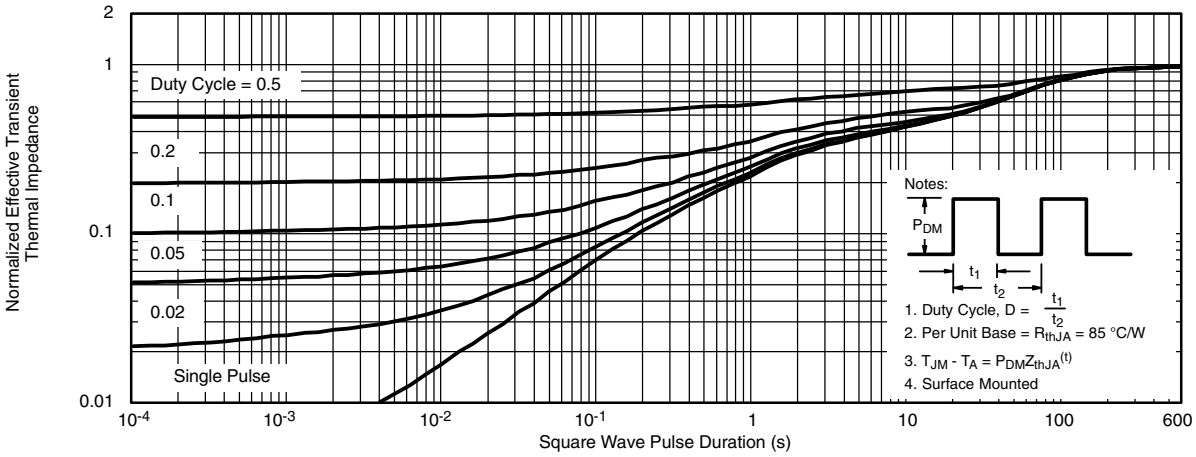


Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

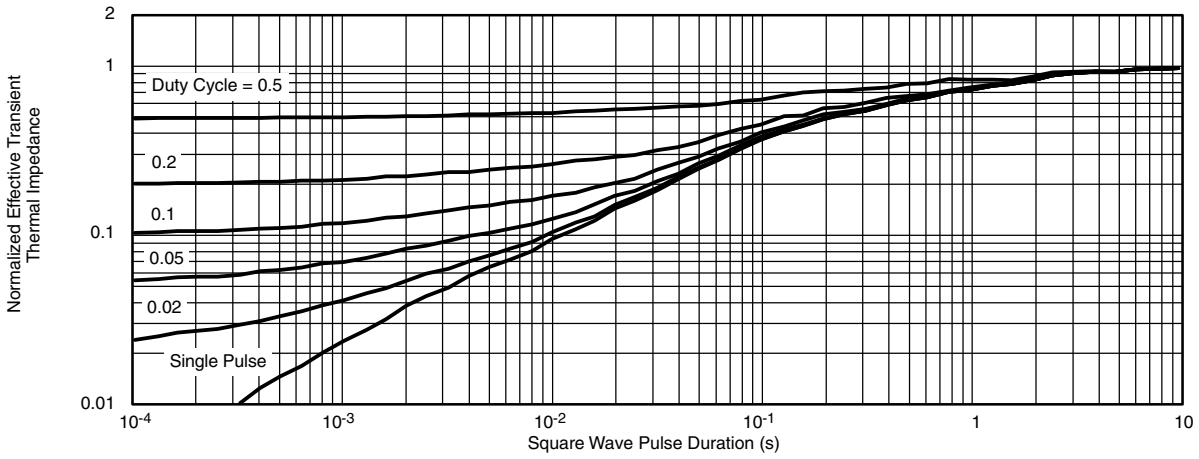


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

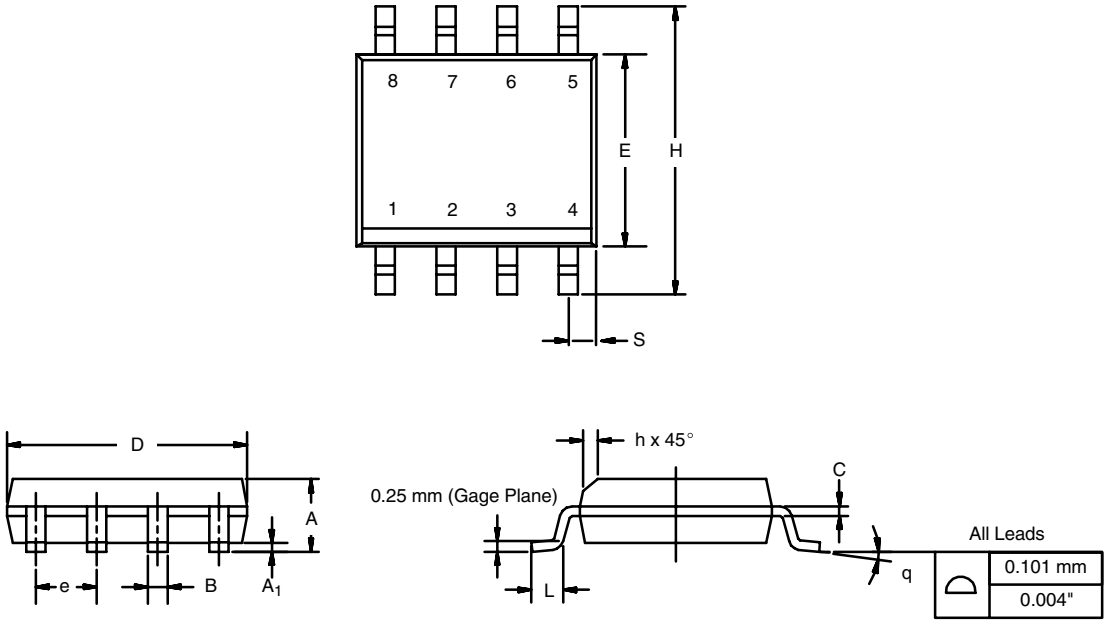
Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

  are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

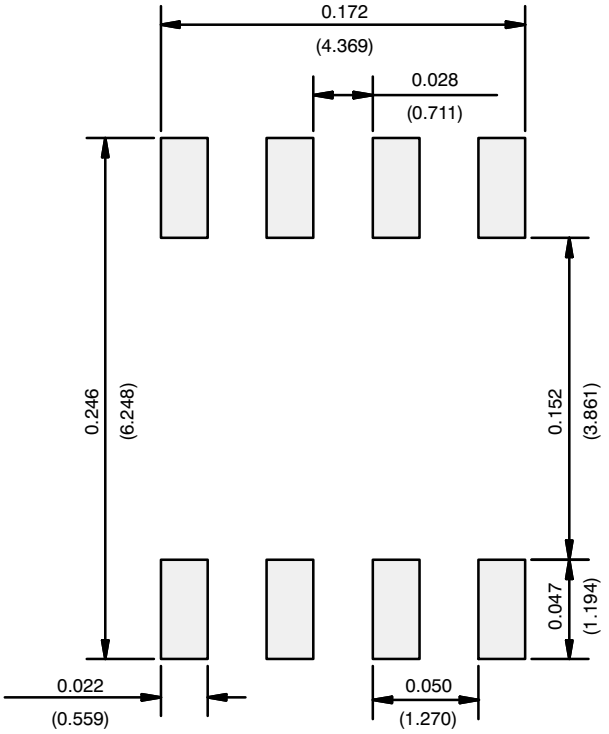
SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A_1	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498				

RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

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